

## AMENDMENTS TO THE CLAIMS

### **1-26. (Canceled)**

**27. (Currently Amended)** A substrate holder for holding a circuit board, comprising:

a main body; and

a holding surface formed on the main body for allowing a circuit board to adhere to the holding surface, wherein the holding surface includes:

a first adhesive holding region which has first surface coarseness and is operable to hold the circuit board with a first tackiness which corresponds to the first surface coarseness; and

a second adhesive holding region which has second surface coarseness different from the first surface coarseness and is operable to hold the circuit board with a second tackiness which corresponds to the second surface coarseness and is different from the first tackiness, said first and second adhesive holding regions being coplanar and capable of holding the circuit board in cooperation;

wherein the first adhesive holding region and the second adhesive holding region are arranged parallel to the surface of said main body;

wherein both a tackiness between the first adhesive holding region and the main body and a tackiness between the second adhesive holding region and the main body are larger than the first tackiness and the second tackiness; and

wherein a through hole for receiving a pin is located in the first adhesive holding region so that the through hole is usable by the pin for peeling off the circuit board; and

wherein the second adhesive holding region is surrounded by the first adhesive holding region.

**28. (Previously Presented)** The substrate holder of claim 27, and further comprising an adhesive material provided on said main body, said first adhesive holding region and said second adhesive holding region being on a surface of said adhesive material.

**29. (Previously Presented)** The substrate holder of claim 28, wherein the first adhesive holding region and the second adhesive holding region are within one area of the adhesive material on said main body.

**30. (Previously Presented)** The substrate holder of claim 29, wherein the first adhesive holding region and the second adhesive holding region are composed of the same adhesive material, and the first adhesive holding region and the second adhesive holding region have different surface undulation characteristics.

**31. (Canceled)**

**32. (Previously Presented)** The substrate holder of claim 28, wherein the first adhesive holding region and the second adhesive holding region are composed of the same adhesive material, and the first adhesive holding region and the second adhesive holding region have different surface undulation characteristics.

**33-38. (Canceled)**

**39. (Previously Presented)** The substrate holder of claim 27, wherein the first tackiness is less than the second tackiness.

**40. (Previously Presented)** The substrate holder of claim 39, wherein an air outlet is provided in the second adhesive region.

**41. (Withdrawn)** The substrate holder of claim 29, wherein the first tackiness is less than the second tackiness and the first adhesive holding region is confined within the second adhesive holding region.

**42. (Previously Presented)** The substrate holder of claim 27, wherein the holding surface comprises a plurality of sets of the first adhesive holding region and the second adhesive holding region.

**43. (Previously Presented)** The substrate holder of claim 28, wherein the adhesive material comprises silicone rubber, polyurethane rubber or fluorine rubber.

**44. (Currently Amended)** A pallet for carrying a circuit board comprising:

a main body; and

a holding surface formed on the main body for allowing a circuit board to adhere to the holding surface, wherein the holding surface includes:

a first adhesive holding region which has first surface coarseness and is operable to hold the circuit board with a first tackiness which corresponds to the first surface coarseness; and

a second adhesive holding region which has second surface coarseness different from the first surface coarseness and is operable to hold the circuit board with a second tackiness which corresponds to the second surface coarseness and is different from the first tackiness, said first and second adhesive regions being coplanar and capable of holding the circuit board in cooperation;

wherein the first adhesive holding region and the second adhesive holding region are arranged parallel to the surface of said main body; and

wherein both a tackiness between the first adhesive holding region and the main body and a tackiness between the second adhesive holding region and the main body are larger than the first tackiness and the second tackiness,-

wherein a through hole for receiving a pin is located in the first adhesive holding region so that the through hole is usable by the pin for peeling off the circuit board; and

wherein the second adhesive holding region is surrounded by the first adhesive holding region.

- 45. (New)** A substrate holder for holding a circuit board, comprising:  
a main body; and  
an adhesive holding layer on the main body having a holding surface for allowing a circuit board to adhere to the adhesive holding layer, wherein the holding surface includes:  
a first adhesive holding region which has first surface coarseness and is operable to hold the circuit board with a first tackiness which corresponds to the first surface coarseness; and  
a second adhesive holding region which has second surface coarseness different from the first surface coarseness and is operable to hold the circuit board with a second tackiness which corresponds to the second surface coarseness and is different from the first tackiness, said first and second adhesive holding regions being coplanar and capable of holding the circuit board in cooperation;  
wherein the first adhesive holding region and the second adhesive holding region are arranged parallel to the surface of said main body;  
wherein a through hole for receiving a pin is located in the first adhesive holding region so that the through hole is usable by the pin for peeling off the circuit board; and  
wherein the second adhesive holding region is surrounded by the first adhesive holding region.
- 46. (New)** The substrate holder of claim 27, wherein the first adhesive holding region and the second adhesive holding region are composed of the same adhesive material, and the first adhesive holding region and the second adhesive holding region have different surface undulation characteristics.
- 47. (New)** The substrate holder of claim 27, wherein the first tackiness is less than the second tackiness.
- 48. (New)** The substrate holder of claim 27, wherein an air outlet is provided in the second adhesive region.

**49. (New)** The substrate holder of claim 27, wherein the holding surface comprises a plurality of sets of the first adhesive holding region and the second adhesive holding region.

**50. (New)** The substrate holder of claim 27, wherein the adhesive holding layer comprises silicone rubber, polyurethane rubber or fluorine rubber.

**51. (New)** The substrate holder of claim 45, wherein the adhesive holding layer is formed on the main body so that the adhesive holding layer remains on the main body upon separation of a circuit board from the holding surface.